

Day : Monday  
Date: 4/12/2004

Time: 09:22:06

PALM INTRANET

**Inventor Name Search Result**

10/026,378

Your Search was:

Last Name = CHOU

First Name = JING-PEI

| Application#           | Patent#       | Status      | Date Filed | Title  | Inventor Name 3       |
|------------------------|---------------|-------------|------------|--|-----------------------|
| 10124575<br>2020167888 | Not<br>Issued | 041<br>mine | 04/16/2002 | METHOD OF TISIN<br>DEPOSITION USING A<br>CHEMICAL VAPOR<br>DEPOSITION (CVD) PROCESS                  | CHOU, JING-PEI<br>IFW |
| 10026378<br>This case  | Not<br>Issued | 071         | 12/21/2001 | METHOD OF TISIN<br>DEPOSITION USING A<br>CHEMICAL VAPOR<br>DEPOSITION PROCESS                        | CHOU, JING-PEI        |
| 09632486               | 6509274       | 150         | 08/04/2000 | METHOD FOR FORMING<br>ALUMINUM LINES OVER<br>ALUMINUM-FILLED VIAS IN<br>A SEMICONDUCTOR<br>SUBSTRATE | CHOU, JING-PEI        |

Inventor Search Completed: No Records to Display.

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**PALM INTRANET**

## Inventor Name Search Result

Your Search was:

Last Name = KAO

First Name = CHIEN-TEH

| Application#    | Patent#    | Status            | Date Filed | Title   | Inventor Name 15                                |
|-----------------|------------|-------------------|------------|---|---|
| <u>60447372</u> | Not Issued | 020               | 02/14/2003 | SUBSTRATE CLEANING WITH HYDROGEN PLASMA   | KAO, CHIEN-TEH                                  |
| <u>60305307</u> | Not Issued | 159               | 07/13/2001 | PULSE NUCLEATION ENHANCED NUCLEATION TECHNIQUE FOR IMPROVED STEP COVERAGE AND BETTER GAP FILL FOR WCVD PROCESS  | KAO, CHIEN-TEH                                  |
| <u>10194442</u> | Not Issued | 160<br><i>abd</i> | 07/12/2002 | PULSED NUCLEATION ENHANCED NUCLEATION TECHNIQUE FOR IMPROVED STEP COVERAGE AND BETTER GAP FILL FOR WCVD PROCESS | KAO, CHIEN-TEH                                  |
| <u>10124575</u> | Not Issued | 041               | 04/16/2002 | METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION (CVD) PROCESS                                      | KAO, CHIEN-TEH                                  |
| <u>10026378</u> | Not Issued | 071               | 12/21/2001 | METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION PROCESS  | KAO, CHIEN-TEH                                  |
| <u>10023125</u> | Not Issued | 019               | 12/17/2001 | PULSE NUCLEATION ENHANCED NUCLEATION TECHNIQUE FOR IMPROVED STEP COVERAGE AND BETTER GAP FILL FOR WCVD PROCESS  | KAO, CHIEN-TEH<br><i>not IFW<br/>no pre-pub</i> |
| <u>09973403</u> | Not Issued | 161<br><i>abd</i> | 10/08/2001 | METHOD OF FORMING A SILICON NITRIDE LAYER ON A SEMICONDUCTOR WAFER  | KAO, CHIEN-TEH                                  |
| <u>09916967</u> | Not Issued | 161<br><i>abd</i> | 07/27/2001 | APPARATUS FOR IMPROVED REMOTE MICROWAVE PLASMA SOURCE FOR USE   | KAO, CHIEN-TEH                                  |

|                 |                |           |                 |   |                |
|-----------------|----------------|-----------|-----------------|---|----------------|
|                 |                |           |                 | WITH SUBSTRATE<br>PROCESSING SYSTEMS  |                |
| <u>09603117</u> | <u>6461435</u> | 150       | 06/22/2000<br>X | SHOWERHEAD WITH<br>REDUCED CONTACT AREA   | KAO, CHIEN-TEH |
| <u>09602657</u> | Not<br>Issued  | 161<br>dd | 01/01/0001      | LID ASSEMBLY FOR A<br>SEMICONDUCTOR<br>PROCESSING CHAMBER   | KAO, CHIEN-TEH |
| <u>09593586</u> | <u>6603269</u> | 150       | 06/13/2000<br>X | RESONANT CHAMBER<br>APPLICATOR FOR REMOTE<br>PLASMA SOURCE  | KAO, CHIEN-TEH |
| <u>09416861</u> | <u>6271148</u> | 150       | 10/13/1999<br>X | METHOD FOR IMPROVED<br>REMOTE MICROWAVE<br>PLASMA SOURCE FOR USE<br>WITH SUBSTRATE<br>PROCESSING SYSTEMS    | KAO, CHIEN-TEH |
| <u>09350810</u> | <u>6645884</u> | 150       | 07/09/1999<br>X | METHOD OF FORMING A<br>SILICON NITRIDE LAYER ON<br>A SUBSTRATE  | KAO, CHIEN-TEH |
| <u>08893922</u> | <u>6125859</u> | 150       | 07/11/1997<br>✓ | METHOD FOR IMPROVED<br>CLEANING OF SUBSTRATE<br>PROCESSING SYSTEMS  | KAO, CHIEN-TEH |
| <u>08839111</u> | <u>6026762</u> | 150       | 04/23/1997<br>✓ | APPARATUS FOR IMPROVED<br>REMOTE MICROWAVE<br>PLASMA SOURCE FOR USE<br>WITH SUBSTRATE<br>PROCESSING SYSTEMS | KAO, CHIEN-TEH |

Inventor Search Completed: No Records to Display.

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|----------------------------------|--|---------------------------------------|
| Last Name                        | First Name                             |                                       |
| <input type="text" value="kao"/> | <input type="text" value="chien-teh"/> | <input type="button" value="Search"/> |

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PALM INTRANET

## Inventor Name Search Result

Your Search was:

Last Name = LAI

First Name = CHIUKIN

*pm*  
*w/ope*  
*chiuse*

| Application#    | Patent#    | Status | Date Filed | Title  | Inventor Name 3     |
|-----------------|------------|--------|------------|--|---------------------|
| <u>60447372</u> | Not Issued | 020    | 02/14/2003 | SUBSTRATE CLEANING WITH HYDROGEN PLASMA                                    | LAI, CHIUKIN STEVEN |
| <u>10124575</u> | Not Issued | 041    | 04/16/2002 | METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION (CVD) PROCESS | LAI, CHIUKIN        |
| <u>10026378</u> | Not Issued | 071    | 12/21/2001 | METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION PROCESS       | LAI, CHIUKIN STEVEN |

Inventor Search Completed: No Records to Display.

Search Another: Inventor

Last Name

First Name

lai

chiukin

Search

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Day : Monday  
Date: 4/12/2004



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**Inventor Name Search Result**

Your Search was:

Last Name = LAI

First Name = STEVEN

| Application#               | Patent#                   | Status         | Date Filed            | Title  | Inventor Name 6                  |
|----------------------------|---------------------------|----------------|-----------------------|--|----------------------------------|
| <u>09559020</u>            | <u>6323705</u>            | 150            | 04/25/2000            | DOUBLE CYCLE LOCK<br>APPROACH IN DELAY LOCK<br>LOOP CIRCUIT                                    | LAI, STEVEN                      |
| <u>09557521</u>            | <u>6333959</u>            | 150            | 04/25/2000            | CROSS FEEDBACK LATCH-<br>TYPE BI-DIRECTIONAL SHIFT<br>REGISTER IN A DELAY LOCK<br>LOOP CIRCUIT | LAI, STEVEN                      |
| <u>09453558</u>            | <u>6281428</u>            | 150            | 12/03/1999            | PHOTOVOLTAIC<br>GENERATOR  | LAI, STEVEN                      |
| <del><u>08848765</u></del> | <del>Not<br/>Issued</del> | <del>161</del> | <del>05/01/1997</del> | <del>TELESCOPING PORTABLE<br/>BACK SCRATCHER</del>   | <del>LAINER, STEVEN<br/>D.</del> |
| <del><u>08638425</u></del> | <del>Not<br/>Issued</del> | <del>161</del> | <del>04/26/1996</del> | <del>BUSINESS BIBS</del>   | <del>LAINER, STEVEN<br/>D.</del> |
| <del><u>08546444</u></del> | <del>Not<br/>Issued</del> | <del>166</del> | <del>10/23/1995</del> | <del>TELESCOPING PORTABLE<br/>BACK SCRATCHER</del>   | <del>LAINER, STEVEN<br/>D.</del> |

Inventor Search Completed: No Records to Display.

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|----------------------------------|-------------------------------------|---------------------------------------|
| Last Name                        | First Name                          |                                       |
| <input type="text" value="lai"/> | <input type="text" value="steven"/> | <input type="button" value="Search"/> |

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**PALM INTRANET**

Time: 09:56:23

## Inventor Name Search Result

Your Search was:

Last Name = CHEN

First Name = FUFA

| Application# | Patent#    | Status | Date Filed | Title   | Inventor Name 10 |
|--------------|------------|--------|------------|---|------------------|
| 10038199     | 6660135    | 150    | 12/21/2001 | STAGED ALUMINUM DEPOSITION PROCESS FOR FILLING VIAS   | CHEN, FUFA       |
| 10026378     | Not Issued | 071    | 12/21/2001 | METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION PROCESS  | CHEN, FUFA       |
| 09721337     | 6332601    | 150    | 11/22/2000 | LIQUID VAPORIZERS FOR SEMICONDUCTOR PROCESSING SYSTEMS  | CHEN, FUFA       |
| 09497787     | 6436820    | 150    | 02/03/2000 | METHOD FOR THE CVD DEPOSITION OF A LOW RESIDUAL HALOGEN CONTENT MULTI-LAYERED TITANIUM NITRIDE FILM HAVING A COMBINED THICKNESS GREATER THAN 1000 ANGSTROMS | CHEN, FUFA       |
| 09421779     | 6364949    | 150    | 10/19/1999 | 300MM CVD CHAMBER DESIGN FOR METAL-ORGANIC THIN FILM DEPOSITION   | CHEN, FUFA       |
| 09340977     | 6352620    | 150    | 06/28/1999 | STAGED ALUMINUM DEPOSITION PROCESS FOR FILLING VIAS   | CHEN, FUFA       |
| 09248869     | 6221174    | 150    | 02/11/1999 | METHOD OF PERFORMING TITANIUM/TITANIUM NITRIDE INTEGRATION  | CHEN, FUFA       |
| 09064359     | 6179277    | 150    | 02/27/1998 | LIQUID VAPORIZER SYSTEMS AND METHODS FOR THEIR USE  | CHEN, FUFA       |
| 08976961     | 6220091    | 150    | 11/24/1997 | LIQUID LEVEL PRESSURE SENSOR AND METHOD   | CHEN, FUFA       |
| 08893811     | 6086676    | 150    | 07/11/1997 | PROGRAMMABLE  | CHEN, FUFA       |

|  |  |  |  |  |  |
|--|--|--|--|--|--|
|  |  |  |  | ELECTRICAL INTERLOCK<br>SYSTEM FOR A VACUUM<br>PROCESSING SYSTEM |  |
|--|--|--|--|--|--|

Inventor Search Completed: No Records to Display.

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**Search Another: Inventor**

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**PALM INTRANET**

## Inventor Name Search Result

Your Search was:

Last Name = CHANG

First Name = MEI

| Application#    | Patent#    | Status | Date Filed | Title  | Inventor Name 51   |
|-----------------|------------|--------|------------|--|--------------------|
| <u>60426134</u> | Not Issued | 020    | 11/14/2002 | APPARATUS AND METHOD FOR HYBRID CHEMICAL PROCESSING  | CHANG, MEI         |
| <u>60333200</u> | Not Issued | 159    | 11/16/2001 | ATOMIC LAYER DEPOSITION OF COPPER USING A REDUCING GAS AND NON-FLUORINATED COPPER PRECURSORS | CHANG, MEI         |
| <u>60325712</u> | Not Issued | 159    | 09/28/2001 | METHOD AND APPARATUS FOR PLASMA CLEANING OF COPPER   | CHANG, MEI         |
| <u>60306027</u> | Not Issued | 159    | 07/16/2001 | ATOMIC LAYER DEPOSITION TiCl <sub>4</sub> TIN AND 300MM ATOMIC LAYER DEPOSITION TUNGSTEN     | CHANG, MEI         |
| <u>29148843</u> | D458962    | 150    | 09/25/2001 | TONER CARTRIDGE  | CHANG, MEI<br>HSIA |
| <u>29148842</u> | D473588    | 150    | 09/25/2001 | TONER CARTRIDGE  | CHANG, MEI<br>HSIA |
| <u>29148841</u> | D458961    | 150    | 09/25/2001 | TONER CARTRIDGE  | CHANG, MEI<br>HSIA |
| <u>29148840</u> | D458960    | 150    | 09/25/2001 | TONER CARTRIDGE  | CHANG, MEI<br>HSIA |
| <u>29148839</u> | D458302    | 150    | 09/25/2001 | TONER CARTRIDGE  | CHANG, MEI<br>HSIA |
| <u>10743876</u> | Not Issued | 019    | 12/24/2003 | ACTIVE MATRIX ORGANIC ELECTROLUMINESCENT PANEL   | CHANG, MEI-YING    |
| <u>10741824</u> | Not Issued | 019    | 12/19/2003 | ENHANCEMENT OF CU LINE RELIABILITY USING THIN ALD TAN FILM TO CAP THE CU LINE                | CHANG, MEI         |
| <u>10717013</u> | Not        | 030    | 11/19/2003 | SUPPORT STAND ASSEMBLY   | CHANG, MEI-LI      |

Pat.  
Design  
NO  
NO  
NO



|                 |                |             |                      |   |                   |
|-----------------|----------------|-------------|----------------------|---|-------------------|
|                 | Issued         |             |                      | FOR A COMPUTER DESK   |                   |
| <u>10716096</u> | Not Issued     | 020         | 11/18/2003           | CHAMBER FOR CONSTRUCTING A FILM ON A SEMICONDUCTOR WAFER  | CHANG, MEI        |
| <u>10712690</u> | Not Issued     | 019<br>1734 | 11/13/2003<br>118/—? | APPARATUS AND METHOD FOR HYBRID CHEMICAL ? PROCESSING   | CHANG, MEI<br>IFW |
| <u>10634662</u> | Not Issued     | 030         | 08/04/2003           | RUTHENIUM LAYER FORMATION FOR COPPER FILM DEPOSITION  | CHANG, MEI        |
| <u>10299212</u> | Not Issued     | 041         | 11/18/2002           | FORMATION OF COMPOSITE TUNGSTEN FILMS   | CHANG, MEI        |
| <u>10295770</u> | Not Issued     | 061         | 11/15/2002           | ATOMIC LAYER DEPOSITION OF COPPER USING A REDUCING GAS AND NON-FLUORINATED COPPER PRECURSORS                                    | CHANG, MEI        |
| <u>10281079</u> | Not Issued     | 041         | 10/25/2002           | GAS DELIVERY APPARATUS FOR ATOMIC LAYER DEPOSITION  | CHANG, MEI        |
| <u>10248113</u> | <u>6608333</u> | 150         | 12/19/2002           | ORGANIC LIGHT EMITTING DIODE DEVICE   | CHANG, MEI-YING   |
| <u>10124575</u> | Not Issued     | 041         | 04/16/2002           | METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION (CVD) PROCESS  | CHANG, MEI        |
| <u>10124309</u> | Not Issued     | 071         | 04/16/2002           | MULTI-STATION DEPOSITION APPARATUS AND METHOD   | CHANG, MEI        |
| <u>10052681</u> | Not Issued     | 094         | 01/17/2002           | RELIABILITY BARRIER INTEGRATION FOR CU APPLICATION  | CHANG, MEI        |
| <u>10050818</u> | Not Issued     | 071         | 01/18/2002           | METHOD OF A HIGH STABILITY SELECTABLE HYDROGENATE CATALYST PRODUCING AND USING FOR DMCHD MANUFACTURING                          | CHANG, MEI-YUAN   |
| <u>10047382</u> | <u>6705246</u> | 150         | 01/14/2002<br>?      | RF POWERED PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION REACTOR AND METHODS OF EFFECTING PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION | CHANG, MEI        |
| <u>10043544</u> | <u>6533894</u> | 150         | 01/10/2002<br>?      | RF POWERED PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION REACTOR AND  | CHANG, MEI        |

|   |            |                        |                         |   |                              |
|---|------------|------------------------|-------------------------|---|------------------------------|
|   |            |                        |                         | METHODS OF EFFECTING PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION                                      |                              |
| 10026378                                | Not Issued | 071                    | 12/21/2001              | METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION PROCESS                                | CHANG, MEI                   |
| 10015433                                | Not Issued | 121                    | 12/12/2001              | METHOD AND APPARATUS FOR CLEANING SUBSTRATES  | CHANG, MEI                   |
| 09965373<br>20030057027                 | Not Issued | 071<br>2814            | 09/26/2001<br>458/1687  | INTEGRATION OF BARRIER LAYER AND SEED LAYER   | CHANG, MEI<br>FFW            |
| 09965370<br>20030059539                 | Not Issued | 041<br>1762            | 09/26/2001<br>427/248.1 | INTEGRATION OF BARRIER LAYER AND SEED LAYER   | CHANG, MEI<br>IFW - Enc Fall |
| 09965369<br>20030057526                 | Not Issued | 120<br>2814            | 09/26/2001<br>257/642   | INTEGRATION OF BARRIER LAYER AND SEED LAYER   | CHANG, MEI<br>NOT FFW        |
| 09964108                                | 6607976    | 150                    | 09/25/2001              | COPPER INTERCONNECT BARRIER LAYER STRUCTURE AND FORMATION METHOD                                    | CHANG, MEI                   |
| 09960469<br>2003 0049991<br>20020197865 | Not Issued | 041<br>2818<br>458/148 | 09/19/2001              | FORMATION OF REFRACTORY METAL NITRIDES USING CHEMISORPTION TECHNIQUES                               | CHANG, MEI<br>NOT FFW        |
| 09949228                                | 6690904    | 150                    | 09/07/2001              | DEVELOPER CONTAINER   | CHANG, MEI<br>HSIA           |
| 09885609                                | Not Issued | 092<br>2918<br>438/679 | 06/20/2001              | SYSTEM AND METHOD TO FORM A COMPOSITE FILM STACK UTILIZING SEQUENTIAL DEPOSITION TECHNIQUES         | CHANG, MEI.<br>FFW           |
| 09882696                                | Not Issued | 161<br>adl             | 06/15/2001              | INTEGRATED BARRIER LAYER STRUCTURE FOR COPPER CONTACT LEVEL METALLIZATION                           | CHANG, MEI                   |
| 09882182                                | Not Issued | 164<br>adl             | 06/18/2001              | PACKAGING STRUCTURE OF A CHIP   | CHANG, MEI-HUI               |
| 09880465                                | Not Issued | 041                    | 06/12/2001              | LOW-RESISTIVITY TUNGSTEN FROM HIGH-PRESSURE CHEMICAL VAPOR DEPOSITION USING METAL-ORGANIC PRECURSOR | CHANG, MEI                   |
| 09874882                                | 6482746    | 150                    | 06/05/2001              | COMPUTER READABLE MEDIUM FOR CONTROLLONG A METHOD OF CLEANING A PROCESS CHAMBER                     | CHANG, MEI                   |

|          |            |                   |                 |   |                |
|----------|------------|-------------------|-----------------|---|----------------|
| 09755009 | Not Issued | 161<br><i>del</i> | 01/05/2001      | DEPOSITION OF TUNGSTEN NITRIDE BY PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION   | CHANG, MEI     |
| 09737154 | 6326690    | 150               | 12/14/2000      | METHOD OF TITANIUM/TITANIUM NITRIDE INTEGRATION   | CHANG, MEI     |
| 09706321 | 6355106    | 150               | 11/03/2000      | DEPOSITION OF COPPER WITH INCREASED ADHESION  | CHANG, MEI     |
| 09670982 | 6235646    | 150               | 09/26/2000<br>? | RF POWERED PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION REACTOR AND METHODS OF EFFECTING PLASMA-ENHANCED CHEMICAL VAPOR DEPOSITION | CHANG, MEI     |
| 09667315 | Not Issued | 161<br><i>del</i> | 09/22/2000      | PROCESS FOR MANUFACTURING A SHOE SOLE   | CHANG, MEI-YUN |
| 09608659 | 6402806    | 150               | 06/30/2000      | METHOD FOR UNREACTED PRECURSOR CONVERSION AND EFFLUENT REMOVAL  | CHANG, MEI     |
| 09598839 | Not Issued | 030               | 06/21/2000      | MULTIPLE FILE SEGMENT PLAYBACK FOR MPEG PRODUCT   | CHANG, MEICHIH |
| 09593018 | 6270621    | 150               | 06/13/2000      | ETCH CHAMBER  | CHANG, MEI     |
| 09569737 | Not Issued | 161<br><i>del</i> | 05/11/2000      | METHOD OF TITANIUM/TITANIUM NITRIDE INTEGRATION   | CHANG, MEI     |
| 09495555 | 6555183    | 150               | 02/01/2000      | PLASMA TREATMENT OF A TITANIUM NITRIDE FILM FORMED BY CHEMICAL VAPOR DEPOSITION   | CHANG, MEI     |
| 09491618 | Not Issued | 160<br><i>del</i> | 01/26/2000      | INLET MANIFOLD AND METHODS FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS                                    | CHANG, MEI     |
| 09330696 | 6548402    | 150               | 06/11/1999      | METHOD OF DEPOSITING A THICK TITANIUM NITRIDE FILM  | CHANG, MEI     |
| 09162336 | 6193813    | 150               | 09/28/1998      | UTILIZATION OF SIH4 SOAK AND PURGE IN DEPOSITION PROCESSES  | CHANG, MEI     |

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Date: 4/12/2004

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**PALM INTRANET**

## Inventor Name Search Result

Your Search was:

Last Name = CHANG

First Name = MEI

| Application#    | Patent#    | Status | Date Filed | Title   | Inventor Name 51 |
|-----------------|------------|--------|------------|---|------------------|
| <u>60478663</u> | Not Issued | 020    | 06/13/2003 | INTEGRATION OF ALD TANTALUM NITRIDE FOR COPPER METALLIZATION  | CHANG, MEI       |
| <u>60477478</u> | Not Issued | 020    | 06/05/2003 | APPARATUS FOR GENERATING A PRECURSOR FOR A SEMICONDUCTOR PROCESSING SYSTEM  | CHANG, MEI       |
| <u>60438479</u> | Not Issued | 020    | 01/07/2003 | ENHANCE OF CU LINE RELIABILITY USING THIN ALD TAN FILM TO CAP THE CU LINE   | CHANG, MEI       |
| <u>60397230</u> | Not Issued | 159    | 07/19/2002 | DEPOSITION APPARATUS  | CHANG, MEI       |
| <u>60385715</u> | Not Issued | 159    | 06/04/2002 | DEPOSITION OF COPPER FILMS  | CHANG, MEI       |
| <u>60385499</u> | Not Issued | 159    | 06/04/2002 | NOBLE METAL LAYER FORMATION FOR COPPER FILM DEPOSITION  | CHANG, MEI       |
| <u>10602836</u> | Not Issued | 030    | 06/24/2003 | MICRODERMABRASION CANISTER RACK SYSTEM  | CHANG, MEI YIN   |
| <u>10447255</u> | Not Issued | 041    | 05/27/2003 | METHOD AND APPARATUS OF GENERATING PDMAT PRECURSOR  | CHANG, MEI       |
| <u>10443648</u> | Not Issued | 030    | 05/22/2003 | NOBLE METAL LAYER FORMATION FOR COPPER FILM DEPOSITION  | CHANG, MEI       |
| <u>10441242</u> | Not Issued | 030    | 05/19/2003 | DEPOSITION OF COPPER FILMS  | CHANG, MEI       |
| <u>10427904</u> | Not Issued | 030    | 05/02/2003 | ORGANIC LIGHT-EMITTING DIODE DEVICE WITH A FUNCTION OF LATERAL LIGHT UTILIZATION, METHOD FOR UTILIZING THE SAME AND | CHANG, MEI-YING  |

|                          |               |             |                                   |   |                     |
|--------------------------|---------------|-------------|-----------------------------------|---|---------------------|
|                          |               |             |                                   | DEVICE WITH INFORMATION<br>DISPLAY AND BACK-LIGHT<br>EFFECT   |                     |
| 10347245                 | Not<br>Issued | 041         | 01/21/2003                        | SERIAL LAMP ASSEMBLY FOR<br>EXTENDING ITS LIFE OF USE   | CHANG, MEI-<br>FANG |
| 10250199                 | Not<br>Issued | 041         | 06/12/2003                        | [ORGANIC LIGHT EMITTING<br>DIODE DISPLAY DEVICE]  | CHANG, MEI-<br>YING |
| 10124309<br>2003 0194493 | Not<br>Issued | 071<br>1734 | 04/16/2002<br>11/1/2002 L. F. Lin | MULTI-STATION DEPOSITION<br>APPARATUS AND METHOD  | CHANG, MEI<br>FFW   |
| 09480313                 | 6193836       | 150         | 01/10/2000                        | CENTER GAS FEED<br>APPARATUS FOR A HIGH<br>DENSITY PLASMA REACTOR   | CHANG, MEI          |
| 09182955                 | 6432479       | 150         | 10/29/1998                        | METHOD FOR IN-SITU, POST<br>DEPOSITION SURFACE<br>PASSIVATION OF A CHEMICAL<br>VAPOR DEPOSITED FILM               | CHANG, MEI          |
| 09179905                 | 5990565       | 150         | 10/28/1998                        | FLIP CHIP PACKAGE   | CHANG<br>MEI LIEN   |
| 08982727                 | 6063441       | 150         | 12/02/1997                        | PROCESSING CHAMBER AND<br>METHOD FOR CONFINING<br>PLASMA  | CHANG, MEI          |
| 08960104                 | 6184150       | 150         | 10/27/1997                        | OXIDE ETCH PROCESS WITH<br>HIGH SELECTIVITY TO<br>NITRIDE SUITABLE FOR USE<br>ON SURFACES OF UNEVEN<br>TOPOGRAPHY | CHANG, MEI          |
| 08939962                 | 5882419       | 150         | 09/29/1997                        | IMPROVED CHEMICAL VAPOR<br>DEPOSITION CHAMBER   | CHANG, MEI          |
| 08939914                 | 5989999       | 150         | 09/26/1997                        | CONSTRUCTION OF A<br>TANTALUM NITRIDE FILM ON<br>A SEMICONDUCTOR WAFER  | CHANG, MEI          |
| 08682844                 | 5834068       | 150         | 07/12/1996                        | WAFER SURFACE<br>TEMPERATURE CONTROL FOR<br>DEPOSITION OF THIN FILMS  | CHANG, MEI          |
| 08677185                 | 6155198       | 150         | 07/09/1996                        | APPARATUS FOR<br>CONSTRUCTING AN OXIDIZED<br>FILM ON A SEMICONDUCTOR<br>WAFER                                     | CHANG, MEI          |
| 08661807                 | Not<br>Issued | 163         | 06/11/1996                        | SHADOW RING FOR<br>SEMICONDUCTOR<br>PROCESSING  | CHANG, MEI          |
| 08439630                 | 5581238       | 150         | 05/12/1995                        | PACIFIER WITH FEVER HEAT<br>ALARM DEVICE  | CHANG, MEI-<br>HUI  |
| 08433107                 | Not<br>Issued | 168         | 05/03/1995                        | CLEANING PROCESS FOR<br>REMOVAL OF DEPOSITS FROM  | CHANG, MEI          |

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|                 |                |                  |                         | THE SUSCEPTOR OF A<br>CHEMICAL VAPOR<br>DEPOSITION APPARATUS   |                           |
| <u>08364022</u> | <u>5482749</u> | 250              | 12/23/1994              | PRETREATMENT PROCESS FOR<br>TREATING ALUMINUM-<br>BEARING SURFACES OF<br>DEPOSITION CHAMBER PRIOR<br>TO DEPOSITION OF TUNGSTEN<br>SILICIDE COATING ON<br>SUBSTRATE THEREIN | CHANG , MEI               |
| <u>08138179</u> | Not<br>Issued  | 166<br><i>WJ</i> | 10/14/1993              | PRETREATMENT PROCESS FOR<br>TREATING ALUMINUM-<br>BEARING SURFACES OF<br>DEPOSITION CHAMBER PRIOR<br>TO DEPOSITION OF TUNGSTEN<br>SILICIDE COATING ON<br>SUBSTRATE THEREIN | CHANG , MEI               |
| <u>08135202</u> | <u>5565382</u> | 150              | 10/12/1993<br><i>WJ</i> | PROCESS AND APPARATUS<br>FOR FORMING TUNGSTEN<br>SILICIDE ON SEMICONDUCTOR<br>WAFER USING<br>DICHLOROSILANE GAS  | CHANG , MEI               |
| <u>08113149</u> | Not<br>Issued  | 169<br><i>WJ</i> | 08/26/1993              | PROCESS FOR SELECTIVE<br>DEPOSITION OF TUNGSTEN ON<br>SEMICONDUCTOR WAFER  | CHANG , MEI               |
| <u>08098538</u> | <u>5449410</u> | 250              | 07/28/1993              | PLASMA PROCESSING<br>APPARATUS   | CHANG , MEI               |
| <u>07899217</u> | <u>5712327</u> | 150              | 06/16/1992              | SOFT GAS PERMEABLE<br>CONTACT LENS HAVING<br>IMPROVED CLINICAL<br>PERFORMANCE  | CHANG , MEI<br><i>ZYH</i> |
| <u>07855124</u> | Not<br>Issued  | 166<br><i>WJ</i> | 03/18/1992              | BROMINE AND IODINE ETCH<br>PROCESS FOR SILICON AND<br>SILICIDES  | CHANG , MEI               |
| <u>07823942</u> | <u>5304248</u> | 150              | 01/22/1992              | PASSIVE SHIELD FOR CVD<br>WAFER PROCESSING WHICH<br>PROVIDES FRONTSIDE EDGE<br>EXCLUSION AND PREVENTS<br>BACKSIDE DEPOSITIONS  | CHANG , MEI               |
| <u>07587523</u> | Not<br>Issued  | 168<br><i>WJ</i> | 09/21/1990              | BROMINE AND IODINE ETCH<br>PROCESS FOR SILICON AND<br>SILICIDES  | CHANG , MEI               |
| <u>07551156</u> | Not<br>Issued  | 166<br><i>WJ</i> | 07/11/1990              | SOFT GAS PERMEABLE<br>CONTACT LENS HAVING<br>IMPROVED CLINICAL<br>PERFORMANCE  | CHANG , MEI-<br>ZYH       |

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| <u>07544934</u> | Not Issued | 161<br><i>OK</i> | 06/28/1990 | SOFT GAS PERMEABLE CONTACT LENS HAVING IMPROVED CLINICAL PERFORMANCE  | CHANG , MEI ZYH |
| <u>07407261</u> | Not Issued | 161              | 09/14/1989 | SOFT GAS PERMEABLE CONTACT LENS HAVING IMPROVED SURFACE WETTABILITY   | CHANG , MEI Z.  |
| <u>07398689</u> | Not Issued | 166<br><i>OK</i> | 08/25/1989 | CLEANING PROCESS FOR REMOVAL OF DEPOSITS FROM THE SUSCEPTOR OF A CHEMICAL VAPOR DEPOSITION APPARATUS  | CHANG , MEI     |
| <u>07398239</u> | 5075256    | 250              | 08/25/1989 | PROCESS FOR REMOVING DEPOSITS FROM BACKSIDE AND END EDGE OF SEMICONDUCTOR WAFER WHILE PREVENTING REMOVAL OF MATERIALS FROM FRONT SURFACE OF WAFER | CHANG , MEI     |
| <u>07381587</u> | Not Issued | 161<br><i>OK</i> | 07/18/1989 | SOFT GAS PERMEABLE CONTACT LENS HAVING IMPROVED SURFACE WETTABILITY   | CHANG , MEI Z.  |
| <u>07343035</u> | Not Issued | 166              | 04/25/1989 | MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR AND METHOD  | CHANG , MEI     |
| <u>07251928</u> | Not Issued | 166              | 09/29/1988 | BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES   | CHANG , MEI     |
| <u>07227302</u> | Not Issued | 161              | 08/02/1988 | DUAL LAYERED CONTACT LENSES   | CHANG , MEI     |
| <u>07147594</u> | Not Issued | 164              | 01/22/1988 | MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR   | CHANG , MEI     |
| <u>07132174</u> | Not Issued | 161<br><i>OK</i> | 12/14/1987 | WETTABLE, HYDROPHILIC, SOFT AND OXYGEN PERMEABLE COPOLYMER COMPOSITIONS   | CHANG , MEI ZYH |
| <u>07085424</u> | 4854263    | 150              | 08/14/1987 | INLET MANIFOLD AND METHODS FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS  | CHANG , MEI     |
| <u>07067210</u> | Not Issued | 166<br><i>OK</i> | 06/26/1987 | REACTOR CHAMBER SELF-CLEANING PROCESS   | CHANG , MEI     |
| <u>07001149</u> | Not        | 169<br><i>OK</i> | 01/07/1987 | WETTABLE, SOFT AND  | CHANG , MEI Z.  |

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|                 | Issued        | <i>off</i>        |            | OXYGEN PERMEABLE<br>COPOLYMER COMPOSITIONS                      |             |
| <u>06944843</u> | Not<br>Issued | 166               | 12/19/1986 | MAGNETIC FIELD-ENHANCED<br>PLASMA ETCH REACTOR                  | CHANG , MEI |
| <u>06944491</u> | Not<br>Issued | 166<br><i>ala</i> | 12/19/1986 | BROMINE AND IODINE ETCH<br>PROCESS FOR SILICON AND<br>SILICIDES | CHANG , MEI |

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| Application# | Patent#    | Status | Date Filed | Title  | Inventor Name 51 |
|--------------|------------|--------|------------|--|------------------|
| 09311449     | 6179925    | 150    | 05/14/1999 | METHOD AND APPARATUS FOR IMPROVED CONTROL OF PROCESS AND PURGE MATERIAL IN SUBSTRATE PROCESSING SYSTEM | CHANG , MEI      |
| 09030555     | 6171661    | 150    | 02/25/1998 | DEPOSITION OF COPPER WITH INCREASED ADHESION   | CHANG , MEI      |
| 09023866     | 6079356    | 150    | 02/13/1998 | REACTOR OPTIMIZED FOR CHEMICAL VAPOR DEPOSITION OF TITANIUM  | CHANG , MEI      |
| 09023852     | 6106625    | 150    | 02/13/1998 | REACTOR USEFUL FOR CHEMICAL VAPOR DEPOSITION OF TITANIUM NITRIDE                                       | CHANG , MEI      |
| 09008796     | 6291343    | 150    | 01/20/1998 | PLASMA ANNEALING OF SUBSTRATES TO IMPROVE ADHESION   | CHANG , MEI      |
| 09001627     | Not Issued | 161    | 12/31/1997 | ELECTRIC CONNECTOR STRUCTURE   | CHANG , MEI LAN  |
| 08996735     | 6099649    | 150    | 12/23/1997 | CHEMICAL VAPOR DEPOSITION HOT-TRAP FOR UNREACTED PRECURSOR CONVERSION AND EFFLUENT REMOVAL             | CHANG , MEI      |
| 08884811     | 6309713    | 150    | 06/30/1997 | DEPOSITION OF TUNGSTEN NITRIDE BY PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION                            | CHANG , MEI      |
| 08857847     | 5964947    | 150    | 05/16/1997 | REMOVABLE PUMPING CHANNEL LINERS WITHIN A CHEMICAL VAPOR DEPOSITION CHAMBER                            | CHANG , MEI      |
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| 08764471 | 6297152    | 150 | 12/12/1996 | CVD PROCESS FOR DCS-BASED TUNGSTEN SILICIDE   | CHANG, MEI |
| 08755219 | Not Issued | 168 | 11/22/1996 | HIGH TEMPERATURE RESISTIVE HEATER   | CHANG, MEI |
| 08746178 | 5773100    | 150 | 11/06/1996 | PECVD OF SILICON NITRIDE FILMS  | CHANG, MEI |
| 08743929 | 5817576    | 150 | 11/05/1996 | UTILIZATION OF SIH <sub>4</sub> SOAK AND PURGE IN DEPOSITION PROCESSES                                | CHANG, MEI |
| 08734978 | 6663713    | 150 | 10/22/1996 | METHOD AND APPARATUS FOR FORMING A THIN POLYMER LAYER ON AN INTEGRATED CIRCUIT STRUCTURE              | CHANG, MEI |
| 08717780 | 6066836    | 150 | 09/23/1996 | HIGH TEMPERATURE RESISTIVE HEATER FOR A PROCESS CHAMBER   | CHANG, MEI |
| 08680724 | 5846332    | 150 | 07/12/1996 | THERMALLY FLOATING PEDESTAL COLLAR IN A CHEMICAL VAPOR DEPOSITION CHAMBER                             | CHANG, MEI |
| 08678490 | Not Issued | 163 | 07/09/1996 | METHOD FOR CLEANING TUNGSTEN CVD CHAMBERS USING MOLECULAR FLUORINE WITHOUT PLASMA EXCITATION          | CHANG, MEI |
| 08666976 | 5780360    | 150 | 06/20/1996 | DICHLOROSILANE PURGE IN SILICIDE DEPOSITION PROCESSES   | CHANG, MEI |
| 08639411 | 5874362    | 150 | 04/29/1996 | BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES   | CHANG, MEI |
| 08605809 | 6103014    | 150 | 02/23/1996 | CHEMICAL VAPOR DEPOSITION CHAMBER   | CHANG, MEI |
| 08570764 | Not Issued | 161 | 12/12/1995 | CENTER GAS FEED APPARATUS FOR A HIGH DENSITY PLASMA REACTOR   | CHANG, MEI |
| 08565184 | Not Issued | 166 | 11/28/1995 | OXIDE ETCH PROCESS WITH HIGH SELECTIVITY TO NITRIDE SUITABLE FOR USE ON SURFACES OF UNEVEN TOPOGRAPHY | CHANG, MEI |
| 08551397 | Not Issued | 161 | 11/01/1995 | LOW TEMPERATURE PROCESS FOR CVD FORMATION OF LOW RESISTIVITY TITANIUM                                 | CHANG, MEI |

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|                 |                | <i>all</i>        |                 | NITRIDE ON A SEMICONDUCTOR WAFER  |             |
| <u>08453135</u> | Not Issued     | 166<br><i>all</i> | 05/24/1995      | INLET MANIFOLD AND METHOD FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS                       | CHANG , MEI |
| <u>08450604</u> | Not Issued     | 166<br><i>all</i> | 05/25/1995      | SHADOW RING FOR SEMICONDUCTOR PROCESSING  | CHANG , MEI |
| <u>08438820</u> | Not Issued     | 161<br><i>all</i> | 05/11/1995      | APPARATUS FOR FORMING TUNGSTEN SILICIDE ON SEMICONDUCTOR WAFER USING DICHLOROSILANE GAS                           | CHANG , MEI |
| <u>08342522</u> | <u>5856240</u> | 150               | 11/21/1994<br>? | CHEMICAL VAPOR DEPOSITION OF A THIN FILM ONTO A SUBSTRATE   | CHANG , MEI |
| <u>08327126</u> | 6123864        | 150               | 10/21/1994      | ETCH CHAMBER  | CHANG , MEI |
| <u>08229863</u> | Not Issued     | 166<br><i>all</i> | 04/19/1994      | BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES   | CHANG , MEI |
| <u>08218209</u> | 5851299        | 150               | 03/25/1994      | PASSIVE SHIELD FOR CVD WAFER PROCESSING WHICH PROVIDES FRONTSIDE EDGE EXCLUSION AND PREVENTS BACKSIDE DEPOSITIONS | CHANG , MEI |
| <u>08200862</u> | 5695568        | 150               | 02/23/1994      | CHEMICAL VAPOR DEPOSITION CHAMBER   | CHANG , MEI |
| <u>08187231</u> | 5421401        | 150               | 01/25/1994      | COMPOUND CLAMP RING FOR SEMICONDUCTOR WAFERS  | CHANG , MEI |
| <u>08145432</u> | Not Issued     | 163<br><i>all</i> | 10/29/1993      | SHADOW RING FOR SEMICONDUCTOR PROCESSING  | CHANG , MEI |
| <u>08136529</u> | Not Issued     | 166<br><i>all</i> | 10/14/1993      | DEPOSITION OF ADHERENT TUNGSTEN SILICIDE FILMS FROM DICHLOROSILANE AND TUNGSTEN HEXAFLUORIDE                      | CHANG , MEI |
| <u>08113025</u> | Not Issued     | 161<br><i>all</i> | 08/27/1993      | PROCESS FOR SELECTIVE DEPOSITION OF TUNGSTEN ON SEMICONDUCTOR WAFER   | CHANG , MEI |
| <u>08091698</u> | Not            | 166<br><i>all</i> | 07/14/1993      | LOW TEMPERATURE   | CHANG , MEI |

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|                 | Issued        | <i>ch</i>        |            | PROCESS FOR CVD<br>FORMATION OF LOW<br>RESISTIVITY TITANIUM<br>NITRIDE ON A<br>SEMICONDUCTOR WAFER  |             |
| <u>08083420</u> | Not<br>Issued | 166<br><i>ch</i> | 06/28/1993 | PROCESS FOR UNIFORM<br>DEPOSITION OF TUNGSTEN<br>SILICIDE ON<br>SEMICONDUCTOR WAFERS<br>BY TREATMENT OF<br>SUSCEPTOR HAVING<br>ALUMINUM NITRIDE<br>SURFACE THEREON WITH<br>TUNGSTEN SILICIDE AFTER<br>CLEANING OF SUSCEPTOR | CHANG , MEI |
| <u>08042961</u> | Not<br>Issued | 166<br><i>ch</i> | 04/05/1993 | CHEMICAL VAPOR<br>DEPOSITION CHAMBER  | CHANG , MEI |
| <u>07947212</u> | 5316278       | 150              | 09/18/1992 | CLAMPING RING APPARATUS<br>FOR PROCESSING<br>SEMICONDUCTOR WAFERS   | CHANG , MEI |
| <u>07894180</u> | 5207836       | 150              | 06/03/1992 | CLEANING PROCESS FOR<br>REMOVAL OF DEPOSITS<br>FROM THE SUSCEPTOR OF A<br>CHEMICAL VAPOR<br>DEPOSITION APPARATUS  | CHANG , MEI |
| <u>07809050</u> | Not<br>Issued | 166<br><i>ch</i> | 12/17/1991 | INLET MANIFOLD AND<br>METHODS FOR INCREASING<br>GAS DISSOCIATION AND FOR<br>PECVD OF DIELECTRIC FILMS   | CHANG , MEI |
| <u>07760848</u> | 5215619       | 150              | 09/17/1991 | MAGNETIC FIELD-<br>ENHANCED PLASMA ETCH<br>REACTOR  | CHANG , MEI |
| <u>07759319</u> | 5213650       | 150              | 09/13/1991 | APPARATUS FOR REMOVING<br>DEPOSITS FROM BACKSIDE<br>AND END EDGE OF<br>SEMICONDUCTOR WAFER<br>WHILE PREVENTING<br>REMOVAL OF MATERIALS<br>FROM FRONT SURFACE OF<br>WAFER  | CHANG , MEI |
| <u>07709809</u> | Not<br>Issued | 166<br><i>ch</i> | 05/31/1991 | BROMINE AND IODINE ETCH<br>PROCESS FOR SILICON AND<br>SILICIDES   | CHANG , MEI |
| <u>07622664</u> | Not<br>Issued | 161<br><i>ch</i> | 12/05/1990 | PASSIVE SHIELD FOR CVD<br>WAFER PROCESSING WHICH<br>PROVIDES FRONTSIDE EDGE   | CHANG , MEI |

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| <u>07595793</u> | Not Issued | 166<br><i>abd</i> | 10/09/1990 | MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR                               | CHANG, MEI                |
| <u>07587523</u> | Not Issued | 168               | 09/21/1990 | BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES                 | CHANG, MEI                |
| <u>07345977</u> | Not Issued | 166<br><i>abd</i> | 04/28/1989 | METHODS FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS | CHANG, MEI                |
| <u>07338215</u> | 4943997    | 150               | 04/14/1989 | DEVICE FOR COMMUNICATING A DOORSIDE INTERCOM SET WITH A REMOTE TELEPHONE  | <del>CHANG, MEI-YIN</del> |
| <u>07337607</u> | 4962049    | 150               | 04/13/1989 | PROCESS FOR THE PLASMA TREATMENT OF THE BACKSIDE OF A SEMICONDUCTOR WAFER | CHANG, MEI                |
| <u>07026836</u> | Not Issued | 161               | 03/17/1987 | WETTABLE HYDROPHILIC, SOFT AND OXYGEN PERMEABLE COPOLYMER COMPOSITIONS    | <del>CHANG, MEI Z.</del>  |

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| Application#               | Patent#        | Status            | Date Filed      | Title  | Inventor Name 51            |
|----------------------------|----------------|-------------------|-----------------|--|-----------------------------|
| <u>60067130</u>            | Not Issued     | 159               | 12/02/1997      | CHEMICAL VAPOR DEPOSITION <u>HARDWARE</u>  | CHANG , MEI                 |
| <u>09409477</u>            | 6129044        | 150               | 10/06/1999      | APPARATUS FOR SUBSTRATE PROCESSING WITH IMPROVED THROUGHPUT AND YIELD  | CHANG , MEI                 |
| <u>09379734</u>            | Not Issued     | 161<br><i>abw</i> | 08/24/1999      | GOLF BALL HAVING A IDENTIFICATION LAYER INTER DISPOSED BETWEEN THE CORE AND THE OUTER LAYER  | CHANG , MEI-TZU             |
| <u>09378132</u>            | <u>6159867</u> | 150               | 08/19/1999<br>? | RF POWERED PLASMA ENHANCED <del>CHEMICAL VAPOR DEPOSITION</del> REACTOR AND METHODS OF EFFECTING PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION | CHANG , MEI                 |
| <u>09344825</u>            | <u>6214714</u> | 150               | 06/25/1999      | METHOD OF <u>TITANIUM/TITANIUM NITRIDE</u> INTEGRATION   | CHANG , MEI                 |
| <del><u>09322921</u></del> | 6131992        | 150               | 06/01/1999      | FOLDABLE CHAIR SUPPORTED BY REAR SUPPORTING LEGS   | <del>CHANG , MEI-FANG</del> |
| <u>09314999</u>            | Not Issued     | 163<br><i>abw</i> | 05/19/1999      | UTILIZATION OF <u>SiH<sub>4</sub></u> SOAK AND PURGE IN DEPOSITION PROCESSES   | CHANG , MEI                 |
| <u>09248183</u>            | <u>6365495</u> | 150               | 02/09/1999      | METHOD FOR PERFORMING METALLO-ORGANIC <del>CHEMICAL VAPOR</del> DEPOSITION OF <u>TITANIUM NITRIDE</u> AT REDUCED TEMPERATURE               | CHANG , MEI                 |
| <u>09200104</u>            | Not Issued     | 164<br><i>abw</i> | 11/25/1998      | METHOD FOR CVD WAFER PROCESSING WHICH  | CHANG , MEI                 |

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|                 |                | <i>del</i>        |                          | PROVIDES FRONTSIDE EDGE EXCLUSION AND PREVENTS BACKSIDE DEPOSITIONS   |                 |
| <u>09179904</u> | Not Issued     | 161<br><i>del</i> | 10/28/1998               | IC PACKAGE CAPABLE OF CONDUCTING HEAT/ELECTRICITY AND REDUCING INDUCTANCE   | CHANG, MEI-LIEN |
| <u>09134290</u> | <u>6020270</u> | 150               | 08/14/1998               | BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES   | CHANG, MEI      |
| <u>09108950</u> | <u>6027606</u> | 150               | 06/30/1998               | CENTER GAS FEED APPARATUS FOR A HIGH DENSITY PLASMA REACTOR   | CHANG, MEI      |
| <u>09096996</u> | Not Issued     | 164<br><i>del</i> | 06/13/1998               | CONTROLLED ADDITION OF WATER DURING CHEMICAL VAPOR DEPOSITION OF COPPER TO IMPROVE ADHESION                                     | CHANG, MEI      |
| <u>09092477</u> | <u>6319728</u> | 150               | 06/05/1998               | METHOD FOR TREATING A DEPOSITED FILM FOR RESISTIVITY REDUCTION  | CHANG, MEI      |
| <u>09087083</u> | <u>5957061</u> | 150               | 05/29/1998               | BANQUET TABLE   | CHANG, MEI-FANG |
| <u>09071514</u> | <u>6294466</u> | 150               | 05/01/1998               | HDP-CVD APPARATUS AND PROCESS FOR DEPOSITING TITANIUM FILMS FOR SEMICONDUCTOR DEVICES   | CHANG, MEI      |
| <u>09059734</u> | <u>6040022</u> | 150               | 04/14/1998               | PECVD OF COMPOUNDS OF SILICON FROM SILANE AND NITROGEN  | CHANG, MEI      |
| <u>09055689</u> | <u>6296712</u> | 150               | 04/06/1998               | CHEMICAL VAPOR DEPOSITION HARDWARE AND PROCESS  | CHANG, MEI      |
| <u>09049856</u> | <u>6270859</u> | 150               | 03/27/1998<br><i>TiN</i> | PLASMA TREATMENT OF TITANIUM NITRIDE FORMED BY CHEMICAL VAPOR DEPOSITION  | CHANG, MEI      |
| <u>09026042</u> | <u>6395128</u> | 150               | 02/19/1998<br><i>?</i>   | RF POWERED PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION REACTOR AND METHODS OF EFFECTING PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION | CHANG, MEI      |
| <u>08982872</u> | Not Issued     | 161<br><i>del</i> | 12/02/1997               | IN-SITU, PRECLEAN OF WAFERS PRIOR TO A  | CHANG, MEI      |

|                 |                |                    |                         |   |             |
|-----------------|----------------|--------------------|-------------------------|---|-------------|
|                 |                | <i>abst</i>        |                         | CHEMICAL VAPOR DEPOSITION TITANIUM DEPOSITION STEP  |             |
| <u>08918665</u> | <u>5983906</u> | 150                | 08/22/1997              | METHODS AND APPARATUS FOR A <u>CLEANING PROCESS</u> IN A HIGH TEMPERATURE, CORROSIVE, PLASMA ENVIRONMENT  | CHANG , MEI |
| <u>08884811</u> | <u>6309713</u> | 150                | 06/30/1997<br><i>WN</i> | DEPOSITION OF <u>TUNGSTEN NITRIDE</u> BY PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION  | CHANG , MEI |
| <u>08808246</u> | <u>6699530</u> | 150                | 02/28/1997<br><i>?</i>  | METHOD FOR <u>CONSTRUCTING A FILM ON A</u> SEMICONDUCTOR WAFER  | CHANG , MEI |
| <u>08604351</u> | Not Issued     | 161<br><i>abst</i> | 02/21/1996              | DEPOSITION OF ADHERENT TUNGSTEN SILICIDE FILMS FROM DICHLOROSILANE AND TUNGSTEN HEXAFLUORIDE  | CHANG , MEI |
| <u>08574739</u> | Not Issued     | 161<br><i>abst</i> | 12/19/1995              | PRECONDITIONING PROCESS FOR TREATING DEPOSITION CHAMBER PRIOR TO DEPOSITION OF TUNGSTEN SILICIDE COATING ON ACTIVE SUBSTRATES THEREIN   | CHANG , MEI |
| <u>08504294</u> | <u>5510297</u> | 150                | 08/10/1995              | PROCESS FOR UNIFORM DEPOSITION OF <u>TUNGSTEN SILICIDE</u> ON SEMICONDUCTOR WAFERS BY TREATMENT OF SUSCEPTOR HAVING ALUMINUM NITRIDE SURFACE THEREON WITH TUNGSTEN SILICIDE AFTER CLEANING OF SUSCEPTOR | CHANG , MEI |
| <u>08352265</u> | Not Issued     | 166<br><i>abst</i> | 12/07/1994              | PROCESS FOR UNIFORM DEPOSITION OF TUNGSTEN SILICIDE ON SEMICONDUCTOR WAFERS BY TREATMENT OF SUSCEPTOR HAVING ALUMINUM NITRIDE SURFACE THEREON WITH TUNGSTEN SILICIDE AFTER CLEANING OF SUSCEPTOR        | CHANG , MEI |
| <u>08342670</u> | <u>5516367</u> | 150                | 11/21/1994              | CHEMICAL VAPOR  | CHANG , MEI |



|          |            |     |            |   |            |
|----------|------------|-----|------------|---|------------|
|          |            |     |            | DEPOSITION CHAMBER WITH A PURGE GUIDE.  |            |
| 08326506 | 5855687    | 150 | 10/20/1994 | SUBSTRATE SUPPORT SHIELD IN WAFER PROCESSING REACTORS   | CHANG, MEI |
| 08314161 | Not Issued | 166 | 09/27/1994 | UTILIZATION OF SIH <sub>4</sub> SOAK AND PURGE IN DEPOSITION PROCESSES                                    | CHANG, MEI |
| 08296042 | Not Issued | 161 | 08/23/1994 | METHOD FOR FORMING LOW RESISTANCE AND LOW DEFECT DENSITY TUNGSTEN CONTACTS TO SILICON SEMICONDUCTOR WAFER | CHANG, MEI |
| 08272959 | Not Issued | 166 | 07/11/1994 | INLET MANIFOLD AND METHOD FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS               | CHANG, MEI |
| 08085064 | Not Issued | 169 | 06/29/1993 | PLASMA PROCESSING APPARATUS   | CHANG, MEI |
| 08084333 | Not Issued | 166 | 06/28/1993 | BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES   | CHANG, MEI |
| 08078364 | 5356835    | 150 | 06/16/1993 | METHOD FOR FORMING LOW RESISTANCE AND LOW DEFECT DENSITY TUNGSTEN CONTACTS TO SILICON SEMICONDUCTOR WAFER | CHANG, MEI |
| 08071462 | Not Issued | 166 | 06/02/1993 | ETCH CHAMBER  | CHANG, MEI |
| 08032909 | Not Issued | 161 | 03/18/1993 | CLEANING PROCESS FOR REMOVAL OF DEPOSITS FROM THE SUSCEPTOR OF A CHEMICAL VAPOR DEPOSITION APPARATUS      | CHANG, MEI |
| 08031259 | 5326725    | 150 | 03/11/1993 | CLAMPING RING AND SUSCEPTOR THEREFOR  | CHANG, MEI |
| 07968710 | Not Issued | 161 | 10/30/1992 | METHOD FOR PROCESSING SEMICONDUCTOR WAFERS AT TEMPERATURES EXCEEDING 400 C                                | CHANG, MEI |
| 07778326 | 5219485    | 150 | 10/17/1991 | MATERIALS AND METHODS FOR ETCHING SILICIDES, POLYCRYSTALLINE SILICON AND POLYCIDES                        | CHANG, MEI |
| 07707214 | Not        | 166 | 05/23/1991 | CLEANING PROCESS FOR  | CHANG, MEI |

|          |            |            |            |   |             |
|----------|------------|------------|------------|---|-------------|
|          | Issued     |            |            | REMOVAL OF DEPOSITS FROM THE SUSCEPTOR OF A CHEMICAL VAPOR DEPOSITION APPARATUS                           |             |
| 07704523 | 5201990    | 150        | 05/23/1991 | PROCESS FOR TREATING ALUMINUM SURFACES IN A VACUUM APPARATUS  | CHANG , MEI |
| 07677681 | 5250467    | 150        | 03/29/1991 | METHOD FOR FORMING LOW RESISTANCE AND LOW DEFECT DENSITY TUNGSTEN CONTACTS TO SILICON SEMICONDUCTOR WAFER | CHANG , MEI |
| 07455799 | 4960488    | 150        | 12/19/1989 | REACTOR CHAMBER SELF-CLEANING PROCESS   | CHANG , MEI |
| 07444485 | 5043299    | 250        | 12/01/1989 | PROCESS FOR SELECTIVE DEPOSITION OF TUNGSTEN ON SEMICONDUCTOR WAFER                                       | CHANG , MEI |
| 07443811 | 5112435    | 150        | 11/29/1989 | MATERIALS AND METHODS FOR ETCHING SILICIDES, POLYCRYSTALLINE SILICON AND POLYCIDES                        | CHANG , MEI |
| 07411189 | Not Issued | 166<br>and | 09/20/1989 | MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR   | CHANG , MEI |
| 07398653 | 5028565    | 250        | 08/25/1989 | PROCESS FOR CVD DEPOSITION OF TUNGSTEN LAYER ON SEMICONDUCTOR WAFER                                       | CHANG , MEI |
| 07185256 | Not Issued | 166<br>and | 04/19/1988 | MATERIALS AND METHODS FOR ETCHING SILICIDES, POLYCRYSTALLINE SILICON & POLYCIDES                          | CHANG , MEI |
| 07185215 | 4842683    | 150        | 04/25/1988 | MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR   | CHANG , MEI |

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| 09163711     | 6242347    | 150    | 09/30/1998 | METHOD FOR CLEANING A PROCESS CHAMBER   | CHANG , MEI     |
| 09140818     | 6090706    | 150    | 08/26/1998 | PRECONDITIONING PROCESS FOR TREATING DEPOSITION CHAMBER PRIOR TO DEPOSITION OF TUNGSTEN SILICIDE COATING ON ACTIVE SUBSTRATES THEREIN | CHANG , MEI     |
| 08606267     | 5935338    | 150    | 02/23/1996 | CHEMICAL VAPOR DEPOSITION CHAMBER   | CHANG , MEI     |
| 08604351     | Not Issued | 161    | 02/21/1996 | DEPOSITION OF ADHERENT TUNGSTEN SILICIDE FILMS FROM DICHLOROSILANE AND TUNGSTEN HEXAFLUORIDE  | CHANG , MEI     |

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